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Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are Embedded - System On Chip (SoC)?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions, SoCs combine a central

Details	
Product Status	Obsolete
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	64KB
Peripherals	DMA, POR, WDT
Connectivity	EBI/EMI, Ethernet, I²C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	800MHz
Primary Attributes	FPGA - 350K Logic Elements
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FBGA, FC (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5asxbb3d4f40i5n

Advantage	Supporting Feature
Lowest system cost	• Requires as few as four power supplies to operate • Available in thermal composite flip chip ball-grid array (BGA) packaging • Includes innovative features such as Configuration via Protocol (CvP), partial reconfiguration, and design security

Summary of Arria V Features

Table 2: Summary of Features for Arria V Devices

Feature	Description

Technology	• TSMC's 28-nm process technology:
	  • Arria V GX, GT, SX, and ST—28-nm low power (28LP) process
	  • Arria V GZ—28-nm high performance (28HP) process
	• Lowest static power in its class (less than 1.2 W for 500K logic elements (LEs) at 85°C junction under typical conditions)
	• 0.85 V, 1.1 V, or 1.15 V core nominal voltage

Packaging	• Thermal composite flip chip BGA packaging • Multiple device densities with identical package footprints for seamless migration between different device densities • Leaded(1), lead-free (Pb-free), and RoHS-compliant options
High-performance FPGA fabric	• Enhanced 8-input ALM with four registers • Improved routing architecture to reduce congestion and improve compilation time
Internal memory blocks	• M10K—10-kilobits (Kb) memory blocks with soft error correction code (ECC) (Arria V GX, GT, SX, and ST devices only) • M20K—20-Kb memory blocks with hard ECC (Arria V GZ devices only) • Memory logic array block (MLAB)-640-bit distributed LUTRAM where you can use up to 50% of the ALMs as MLAB memory

(1) Contact Altera for availability.

Feature	Description
FPGA General-purpose I/Os (GPIOs)	• 1.6 Gbps LVDS receiver and transmitter • 800 MHz/1.6 Gbps external memory interface • On-chip termination (OCT) • 3.3 V support (2)
External Memory Interface	Memory interfaces with low latency: • Hard memory controller-up to 1.066 Gbps • Soft memory controller-up to 1.6 Gbps
Low-power high-speed serial interface	• 600 Mbps to 12.5 Gbps integrated transceiver speed • Less than 105 mW per channel at 6 Gbps, less than 165 mW per channel at 10 Gbps, and less than 170 mW per channel at 12.5 Gbps • Transmit pre-emphasis and receiver equalization • Dynamic partial reconfiguration of individual channels • Physical medium attachment (PMA) with soft PCS that supports 9.8304 Gbps CPRI (Arria V GT and ST only) • PMA with hard PCS that supports up to 9.8 Gbps CPRI (Arria V GZ only) • Hard PCS that supports 10GBASE-R and 10GBASE-KR (Arria V GZ only)
HPS (Arria V SX and ST devices only)	• Dual-core ARM Cortex-A9 MPCore processor—up to 1.05 GHz maximum frequency with support for symmetric and asymmetric multiprocessing • Interface peripherals—10/100/1000 Ethernet media access control (EMAC), USB 2.0 On-The-GO (OTG) controller, quad serial peripheral interface (QSPI) flash controller, NAND flash controller, Secure Digital/MultiMediaCard (SD/MMC) controller, UART, serial peripheral interface (SPI), I2C interface, and up to 85 HPS GPIO interfaces • System peripherals—general-purpose timers, watchdog timers, direct memory access (DMA) controller, FPGA configuration manager, and clock and reset managers • On-chip RAM and boot ROM • HPS–FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa • FPGA-to-HPS SDRAM controller subsystem—provides a configurable interface to the multiport front end (MPFE) of the HPS SDRAM controller • ARM CoreSight™ JTAG debug access port, trace port, and on-chip trace storage

(2) Arria V GZ devices support 3.3 V with a 3.0 V V_{CCIO}.

Feature	Description
Configuration	• Tamper protection-comprehensive design protection to protect your valuable IP investments • Enhanced advanced encryption standard (AES) design security features • CvP • Partial and dynamic reconfiguration of the FPGA • Active serial (AS) x1 and x4, passive serial (PS), JTAG, and fast passive parallel (FPP) x8, x16, and x32 (Arria V GZ) configuration options • Remote system upgrade

Arria V Device Variants and Packages

Table 3: Device Variants for the Arria V Device Family

Variant	Description
Arria V GX	FPGA with integrated 6.5536 Gbps transceivers that provides bandwidth, cost, and power levels that are optimized for high-volume data and signal-processing applications
Arria V GT	FPGA with integrated 10.3125 Gbps transceivers that provides enhanced high-speed serial I/O bandwidth for cost-sensitive data and signal processing applications
Arria V GZ	FPGA with integrated 12.5 Gbps transceivers that provides enhanced high-speed serial I/O bandwidth for high-performance and cost-sensitive data and signal processing applications
Arria V SX	SoC with integrated ARM-based HPS and 6.5536 Gbps transceivers
Arria V ST	SoC with integrated ARM-based HPS and 10.3125 Gbps transceivers

Arria V GX

This section provides the available options, maximum resource counts, and package plan for the Arria V GX devices.

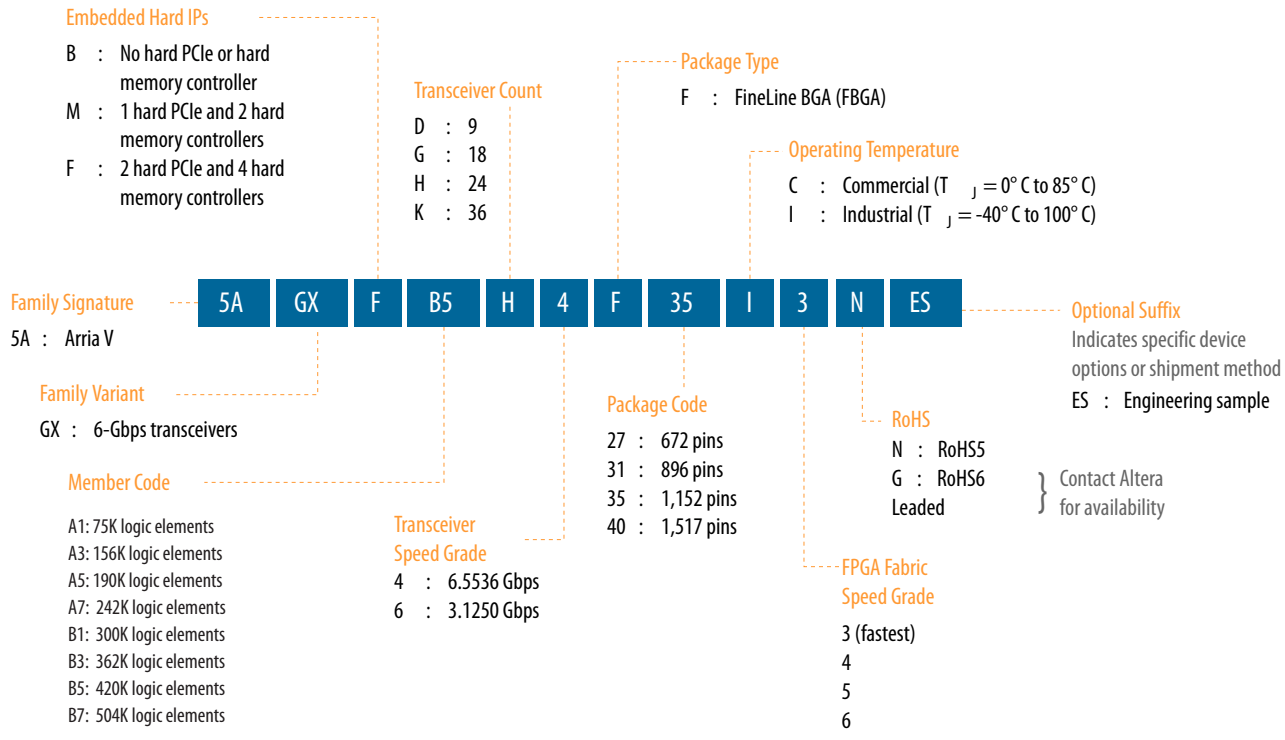
The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Altera Product Selector.

Related Information

Altera Product Selector
Provides the latest information about Altera products.

Available Options

Figure 1: Sample Ordering Code and Available Options for Arria V GX Devices



Maximum Resources

Table 4: Maximum Resource Counts for Arria V GX Devices

Resource		Member Code							
		A1	A3	A5	A7	B1	B3	B5	B7
Logic Elements (LE) (K)		75	156	190	242	300	362	420	504
ALM		28,302	58,900	71,698	91,680	113,208	136,880	158,491	190,240
Register		113,208	235,600	286,792	366,720	452,832	547,520	633,964	760,960
Memory (Kb)	M10K	8,000	10,510	11,800	13,660	15,100	17,260	20,540	24,140
	MLAB	463	961	1,173	1,448	1,852	2,098	2,532	2,906
Variable-precision DSP Block		240	396	600	800	920	1,045	1,092	1,156
18 x 18 Multiplier		480	792	1,200	1,600	1,840	2,090	2,184	2,312
PLL		10	10	12	12	12	12	16	16

Resource		Member Code							
		A1	A3	A5	A7	B1	B3	B5	B7
6 Gbps Transceiver		9	9	24	24	24	24	36	36
GPIO(3)		416	416	544	544	704	704	704	704
LVDS	Transmitter	67	67	120	120	160	160	160	160
	Receiver	80	80	136	136	176	176	176	176
PCIe Hard IP Block		1	1	2	2	2	2	2	2
Hard Memory Controller		2	2	4	4	4	4	4	4

Related Information

High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook
Provides the number of LVDS channels in each device package.

Package Plan

Table 5: Package Plan for Arria V GX Devices

Member Code	F672 (27 mm)		F896 (31 mm)		F1152 (35 mm)		F1517 (40 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
A1	336	9	416	9	—	—	—	—
A3	336	9	416	9	—	—	—	—
A5	336	9	384	18	544	24	—	—
A7	336	9	384	18	544	24	—	—
B1	—	—	384	18	544	24	704	24
B3	—	—	384	18	544	24	704	24
B5	—	—	—	—	544	24	704	36
B7	—	—	—	—	544	24	704	36

Arria V GT

This section provides the available options, maximum resource counts, and package plan for the Arria V GT devices.

(3) The number of GPIOs does not include transceiver I/Os. In the Quartus® Prime software, the number of user I/Os includes transceiver I/Os.

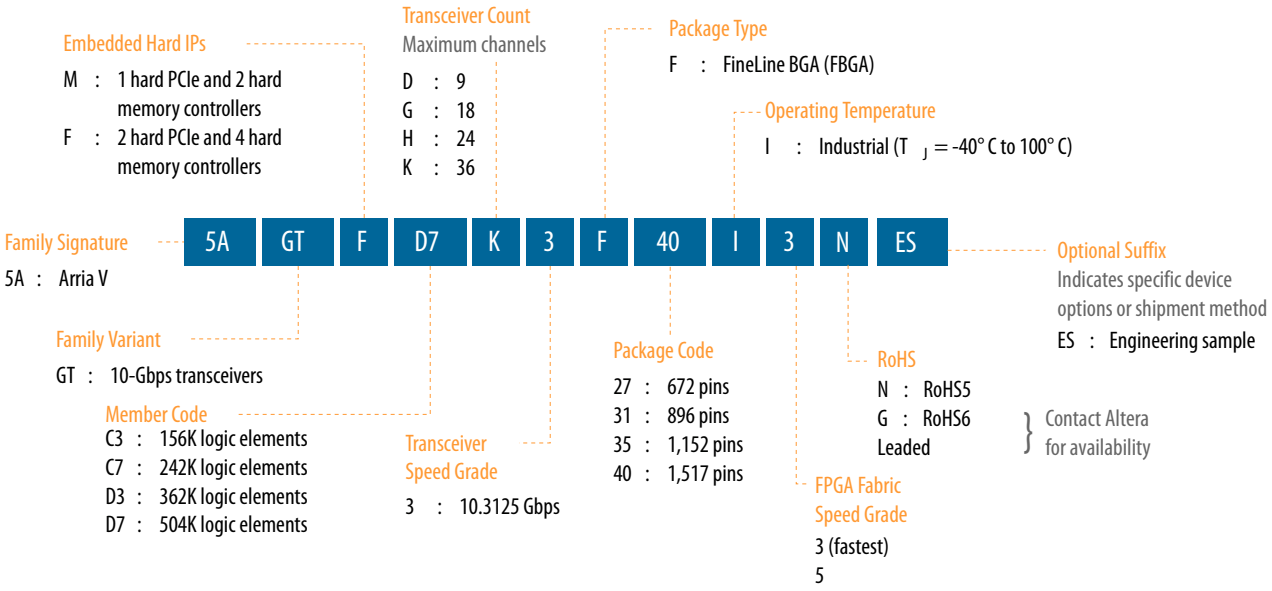
The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Altera Product Selector.

Related Information

Altera Product Selector
Provides the latest information about Altera products.

Available Options

Figure 2: Sample Ordering Code and Available Options for Arria V GT Devices



Maximum Resources

Table 6: Maximum Resource Counts for Arria V GT Devices

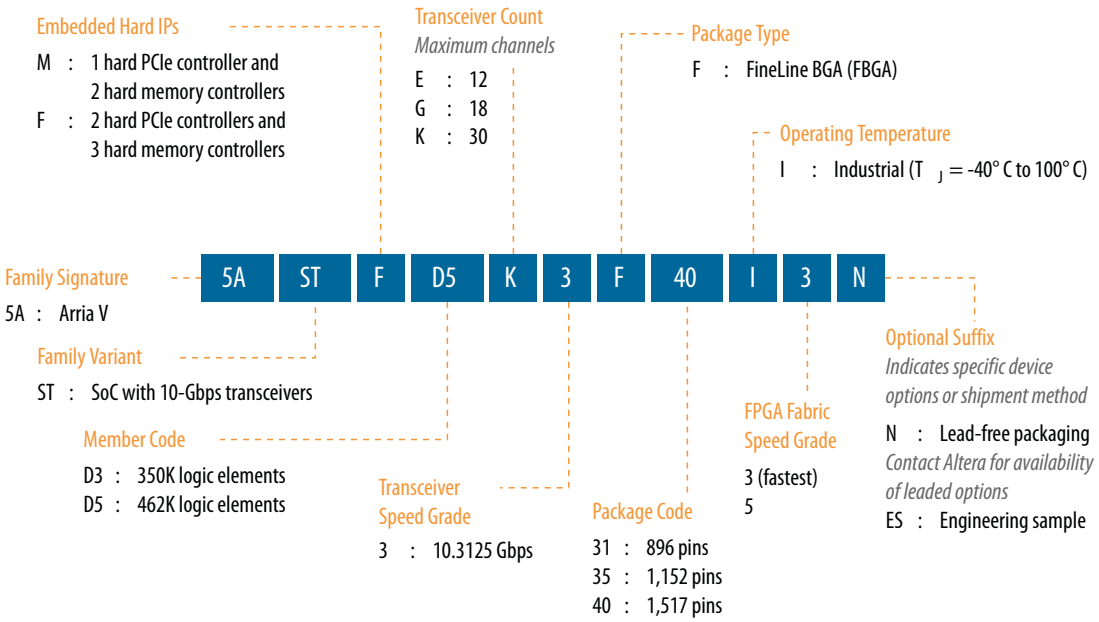
Resource		Member Code			
		C3	C7	D3	D7
Logic Elements (LE) (K)		156	242	362	504
ALM		58,900	91,680	136,880	190,240
Register		235,600	366,720	547,520	760,960
Memory (Kb)	M10K	10,510	13,660	17,260	24,140
	MLAB	961	1,448	2,098	2,906
Variable-precision DSP Block		396	800	1,045	1,156
18 x 18 Multiplier		792	1,600	2,090	2,312
PLL		10	12	12	16

Related Information

Altera Product Selector
Provides the latest information about Altera products.

Available Options

Figure 5: Sample Ordering Code and Available Options for Arria V ST Devices



Maximum Resources

Table 12: Maximum Resource Counts for Arria V ST Devices

Resource		Member Code	
		D3	D5
Logic Elements (LE) (K)		350	462
ALM		132,075	174,340
Register		528,300	697,360
Memory (Kb)	M10K	17,290	22,820
	MLAB	2,014	2,658
Variable-precision DSP Block		809	1,090
18 x 18 Multiplier		1,618	2,180
FPGA PLL		14	14
HPS PLL		3	3
Transceiver	6-Gbps	30	30
	10-Gbps[9]	16	16

Resource		Member Code	
		D3	D5
FPGA GPIO(10)		540	540
HPS I/O		208	208
LVDS	Transmitter	120	120
	Receiver	136	136
PCIe Hard IP Block		2	2
FPGA Hard Memory Controller		3	3
HPS Hard Memory Controller		1	1
ARM Cortex-A9 MPCore Processor		Dual-core	Dual-core

Related Information

- **High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook**
  Provides the number of LVDS channels in each device package.
- **Transceiver Architecture in Arria V Devices**
  Describes 10 Gbps channels usage conditions and SFF-8431 compliance requirements.

Package Plan

Table 13: Package Plan for Arria V ST Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Member Code	F896 (31 mm)				F1152 (35 mm)				F1517 (40 mm)			
	FPGA GPIO	HPS I/O	XCVR		FPGA GPIO	HPS I/O	XCVR		FPGA GPIO	HPS I/O	XCVR	
			6 Gbps	10 Gbps			6 Gbps	10 Gbps			6 Gbps	10 Gbps
D3	250	208	12	6	385	208	18	8	540	208	30	16
D5	250	208	12	6	385	208	18	8	540	208	30	16

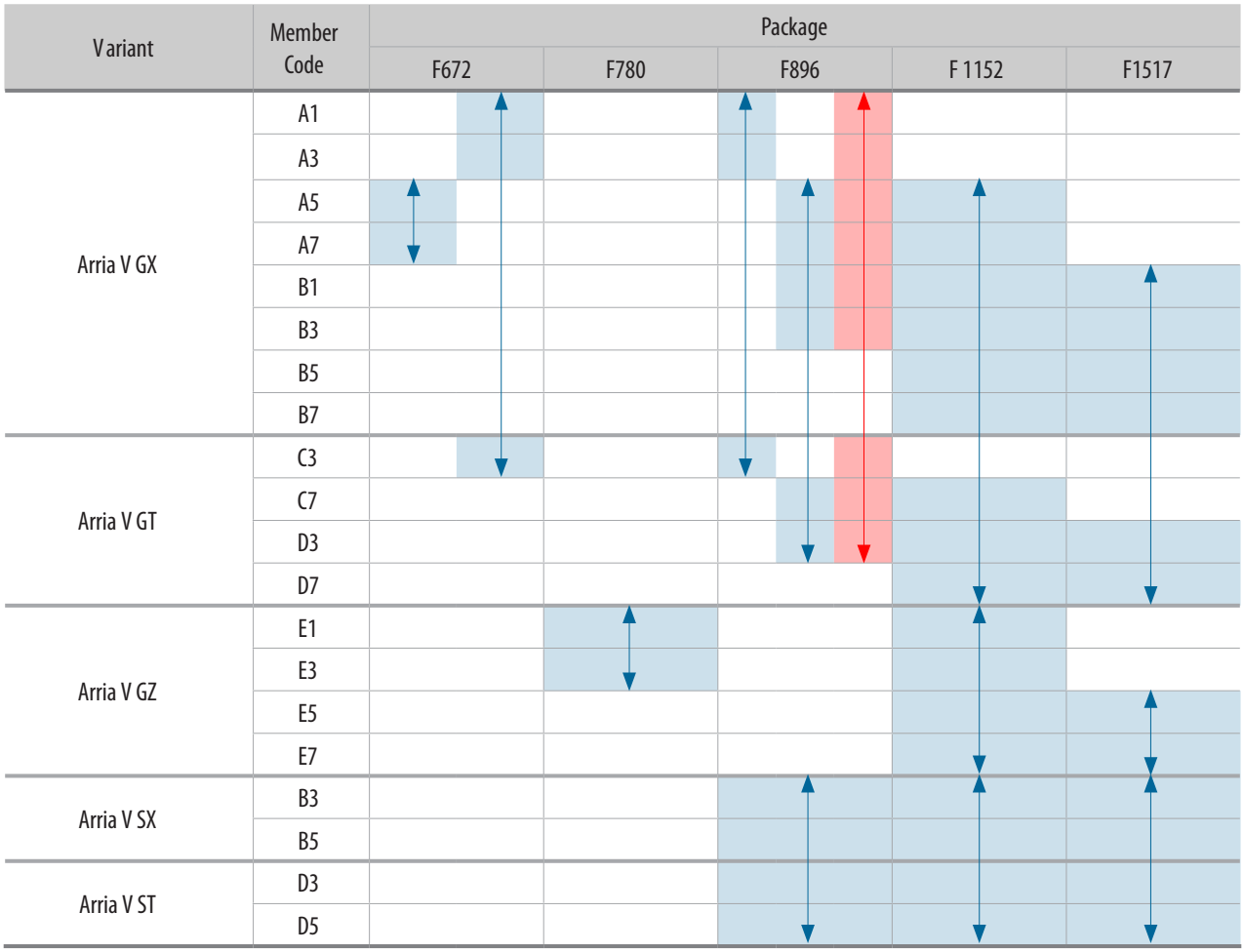
(9) Chip-to-chip connections only. For 10 Gbps channel usage conditions, refer to the Transceiver Architecture in Arria V Devices chapter.

(10) The number of GPIOs does not include transceiver I/Os. In the Quartus Prime software, the number of user I/Os includes transceiver I/Os.

I/O Vertical Migration for Arria V Devices

Figure 6: Vertical Migration Capability Across Arria V Device Packages and Densities

The arrows indicate the vertical migration paths. Some packages have several migration paths. The devices included in each vertical migration path are shaded. You can also migrate your design across device densities in the same package option if the devices have the same dedicated pins, configuration pins, and power pins.



You can achieve the vertical migration shaded in red if you use only up to 320 GPIOs, up to nine 6 Gbps transceiver channels, and up to four 10 Gbps transceiver (for Arria V GT devices). This migration path is not shown in the Quartus Prime software Pin Migration View.

Note: To verify the pin migration compatibility, use the Pin Migration View window in the Quartus Prime software Pin Planner.

Note: Except for Arria V GX A5 and A7, and Arria V GT C7 devices, all other Arria V GX and GT devices require a specific power-up sequence. If you plan to migrate your design from Arria V GX A5 and A7, and Arria V GT C7 devices to other Arria V devices, your design must adhere to the same required power-up sequence.

External Memory Performance

Table 18: External Memory Interface Performance in Arria V Devices

Interface	Voltage (V)	Hard Controller (MHz)	Soft Controller (MHz)	
		Arria V GX, GT, SX, and ST	Arria V GX, GT, SX, and ST	Arria V GZ
DDR3 SDRAM	1.5	533	667	800
	1.35	533	600	800
DDR2 SDRAM	1.8	400	400	400
LPDDR2 SDRAM	1.2	—	400	—
RLDRAM 3	1.2	—	—	667
RLDRAM II	1.8	—	400	533
	1.5	—	400	533
QDR II+ SRAM	1.8	—	400	500
	1.5	—	400	500
QDR II SRAM	1.8	—	400	333
	1.5	—	400	333
DDR II+ SRAM(12)	1.8	—	400	—
	1.5	—	400	—

Related Information

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Altera's External Memory Interface Spec Estimator tool.

HPS External Memory Performance

Table 19: HPS External Memory Interface Performance

The hard processor system (HPS) is available in Arria V SoC devices only.

Interface	Voltage (V)	HPS Hard Controller (MHz)
DDR3 SDRAM	1.5	533
	1.35	533
LPDDR2 SDRAM	1.2	333

(12) Not available as Altera® IP.

Related Information

External Memory Interface Spec Estimator
For the latest information and to estimate the external memory system performance specification, use Altera's External Memory Interface Spec Estimator tool.

Low-Power Serial Transceivers

Arria V devices deliver the industry's lowest power consumption per transceiver channel:

- 12.5 Gbps transceivers at less than 170 mW
- 10 Gbps transceivers at less than 165 mW
- 6 Gbps transceivers at less than 105 mW

Arria V transceivers are designed to be compliant with a wide range of protocols and data rates.

Transceiver Channels

The transceivers are positioned on the left and right outer edges of the device. The transceiver channels consist of the physical medium attachment (PMA), physical coding sublayer (PCS), and clock networks.

The following figures are graphical representations of a top view of the silicon die, which corresponds to a reverse view for flip chip packages. Different Arria V devices may have different floorplans than the ones shown in the figures.

Figure 9: Device Chip Overview for Arria V GX and GT Devices

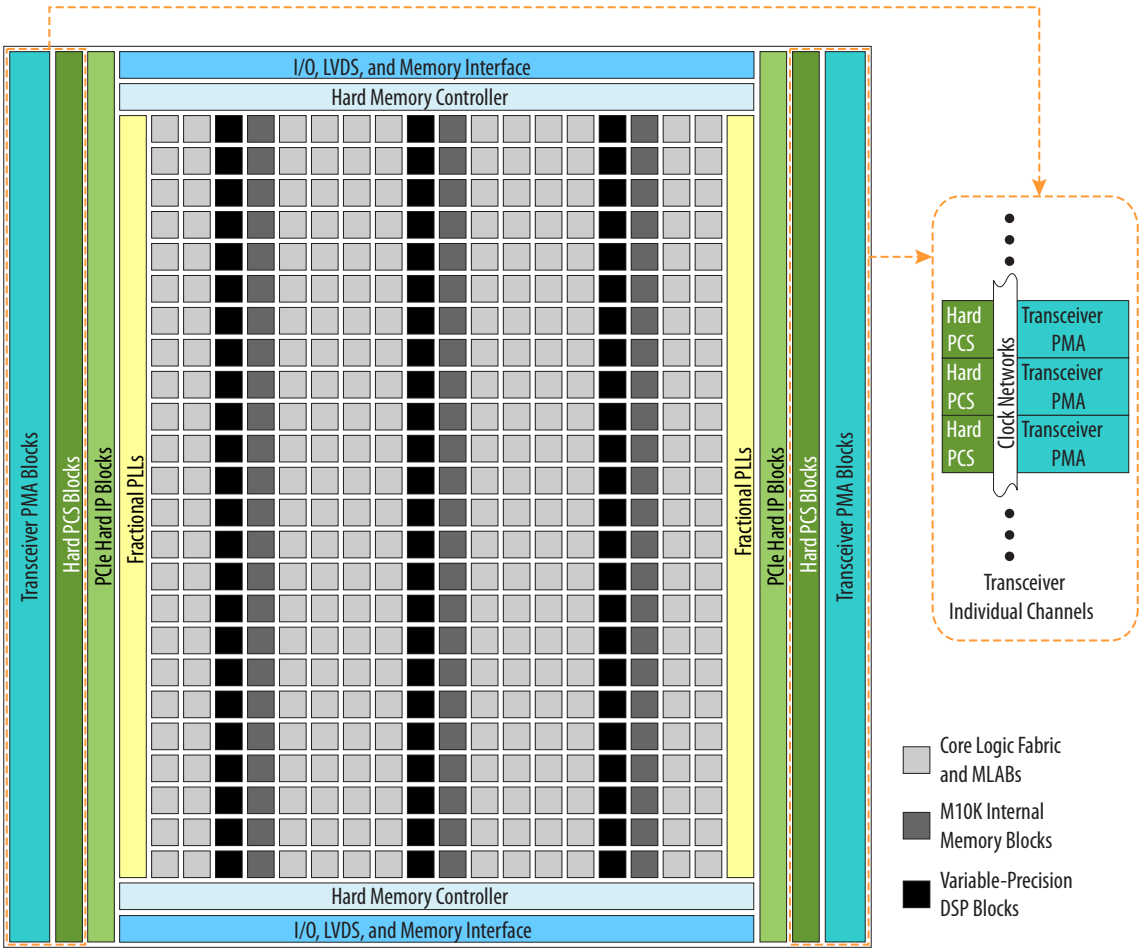


Figure 10: Device Chip Overview for Arria V GZ Devices

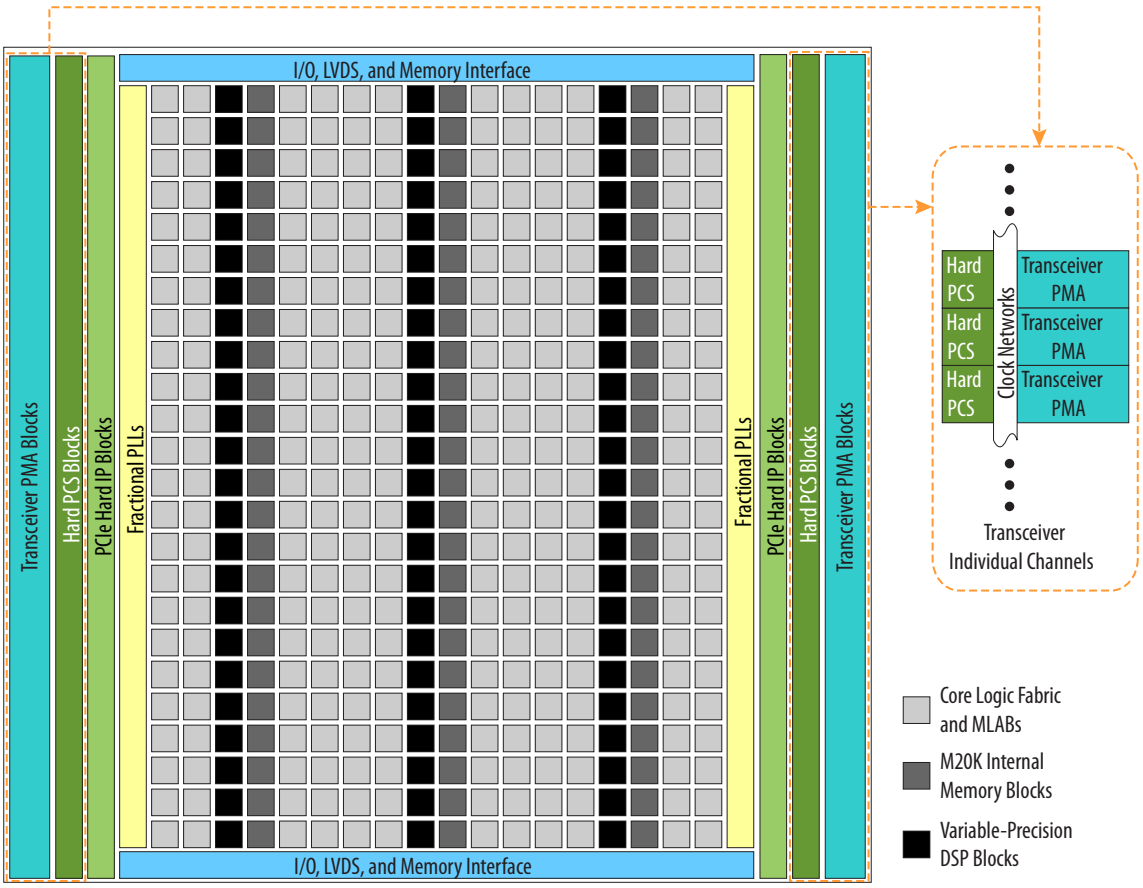
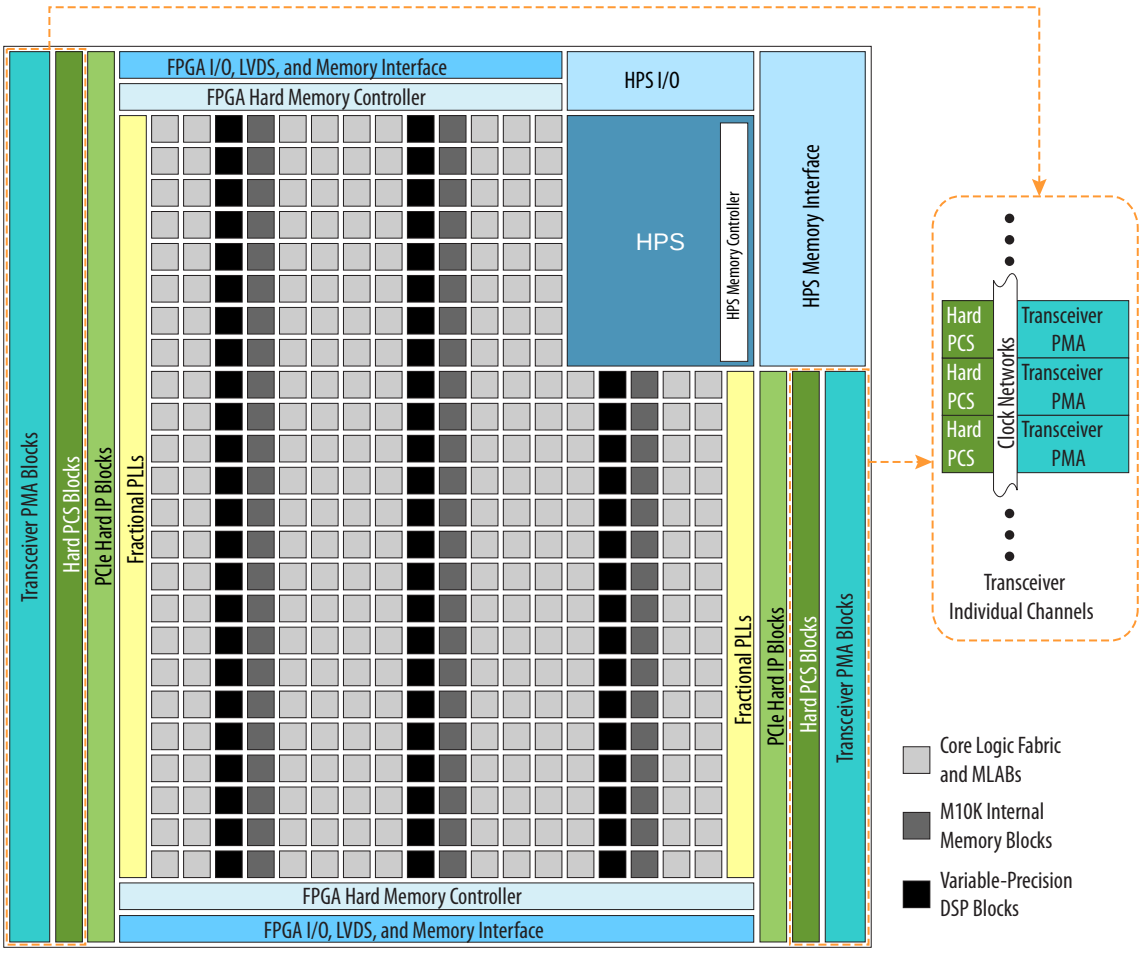


Figure 11: Device Chip Overview for Arria V SX and ST Devices



PMA Features

To prevent core and I/O noise from coupling into the transceivers, the PMA block is isolated from the rest of the chip—ensuring optimal signal integrity. For the transceivers, you can use the channel PLL of an unused receiver PMA as an additional transmit PLL.

Table 20: PMA Features of the Transceivers in Arria V Devices

Features	Capability
Backplane support	• Arria V GX, GT, SX, and ST devices—Driving capability at 6.5536 Gbps with up to 25 dB channel loss • Arria V GZ devices—Driving capability at 12.5 Gbps with up to 16 dB channel loss
Chip-to-chip support	• Arria V GX, GT, SX, and ST devices—Up to 10.3125 Gbps • Arria V GZ devices—Up to 12.5 Gbps

Table 22: Transceiver PCS Features for Arria V GZ Devices

Protocol	Data Rates (Gbps)	Transmitter Data Path Features	Receiver Data Path Features
Custom PHY	0.6 to 9.80	• Phase compensation FIFO • Byte serializer • 8B/10B encoder • Bit-slip • Channel bonding	• Word aligner • Deskew FIFO • Rate match FIFO • 8B/10B decoder • Byte deserializer • Byte ordering
GPON	1.25 and 2.5		
Custom 10G PHY	9.98 to 12.5	• TX FIFO • Gear box • Bit-slip	• RX FIFO • Gear box
PCIe Gen1 (x1, x2 x4, x8)	2.5 and 5.0	• Phase compensation FIFO • Byte serializer • 8B/10B encoder • Bit-slip • Channel bonding • PIPE 2.0 interface to core logic	• Word aligner • Deskew FIFO • Rate match FIFO • 8B/10B decoder • Byte deserializer, • Byte ordering • PIPE 2.0 interface to core logic
PCIe Gen2 (x1, x2, x4, x8)			
PCIe Gen3 (x1, x2, x4, x8)	8.0	• Phase compensation FIFO • 128B/130B encoder • Scrambler • Gear box • Bit-slip	• Block synchronization • Rate match FIFO • 128B/130B decoder • Descrambler • Phase compensation FIFO
10GbE	10.3125	• TX FIFO • 64B/66B encoder • Scrambler • Gear box	• RX FIFO • 64B/66B decoder • Descrambler • Block synchronization • Gear box
Interlaken	3.125 to 12.5	• TX FIFO • Frame generator • CRC-32 generator • Scrambler • Disparity generator • Gear box	• RX FIFO • Frame generator • CRC-32 checker • Frame decoder • Descrambler • Disparity checker • Block synchronization • Gear box

SoC with HPS

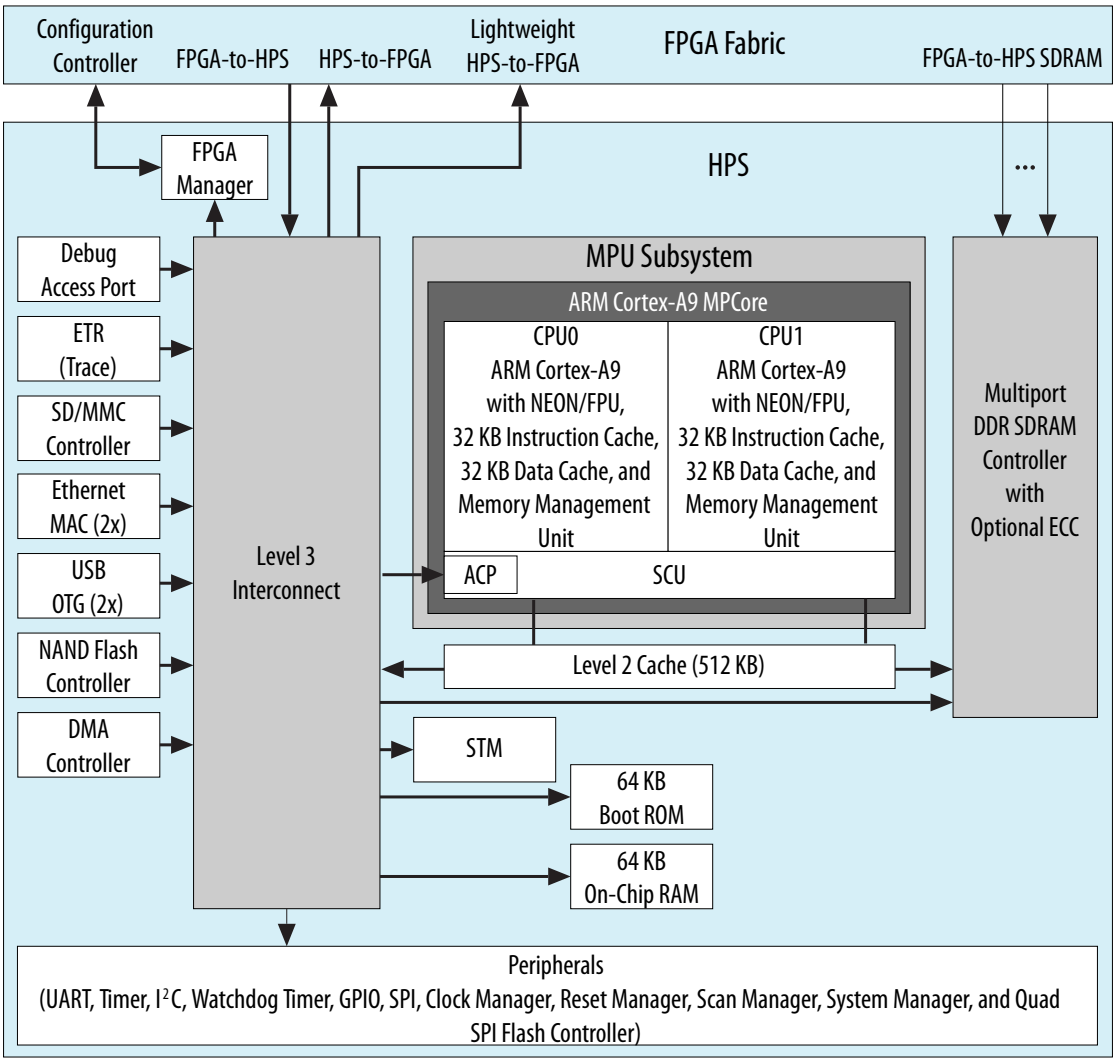
Each SoC combines an FPGA fabric and an HPS in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

HPS Features

The HPS consists of a dual-core ARM Cortex-A9 MPCore processor, a rich set of peripherals, and a shared multiport SDRAM memory controller, as shown in the following figure.

Figure 12: HPS with Dual-Core ARM Cortex-A9 MPCore Processor



You can configure the FPGA fabric and boot the HPS independently, in any order, providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or partially reconfigure the FPGA fabric at any time under software control. The HPS can also configure other FPGAs on the board through the FPGA configuration controller.
- You can power up both the HPS and the FPGA fabric together, configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.

Note: Although the FPGA fabric and HPS are on separate power domains, the HPS must remain powered up during operation while the FPGA fabric can be powered up or down as required.

Related Information

- **Arria V GT, GX, ST, and SX Device Family Pin Connection Guidelines**
  Provides detailed information about power supply pin connection guidelines and power regulator sharing.
- **Arria V GZ Device Family Pin Connection Guidelines**
  Provides detailed information about power supply pin connection guidelines and power regulator sharing.

Hardware and Software Development

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Qsys system integration tool in the Quartus Prime software.

For software development, the ARM-based SoC devices inherit the rich software development ecosystem available for the ARM Cortex-A9 MPCore processor. The software development process for Altera SoCs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux, VxWorks®, and other operating systems is available for the SoCs. For more information on the operating systems support availability, contact the Altera sales team.

You can begin device-specific firmware and software development on the Altera SoC Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board that runs on a PC. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

Related Information

Altera Worldwide Sales Support

Dynamic and Partial Reconfiguration

The Arria V devices support dynamic reconfiguration and partial reconfiguration.

Dynamic Reconfiguration

The dynamic reconfiguration feature allows you to dynamically change the transceiver data rates, PMA settings, or protocols of a channel, without affecting data transfer on adjacent channels. This feature is ideal for applications that require on-the-fly multiprotocol or multirate support. You can reconfigure the PMA, PCS, and PCIe hard IP blocks with dynamic reconfiguration.

Partial Reconfiguration

Note: Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Altera for support.

Partial reconfiguration allows you to reconfigure part of the device while other sections of the device remain operational. This capability is important in systems with critical uptime requirements because it allows you to make updates or adjust functionality without disrupting services.

Apart from lowering cost and power consumption, partial reconfiguration increases the effective logic density of the device because placing device functions that do not operate simultaneously is not necessary. Instead, you can store these functions in external memory and load them whenever the functions are required. This capability reduces the size of the device because it allows multiple applications on a single device—saving the board space and reducing the power consumption.

Altera simplifies the time-intensive task of partial reconfiguration by building this capability on top of the proven incremental compile and design flow in the Quartus Prime design software. With the Altera solution, you do not need to know all the intricate device architecture details to perform a partial reconfiguration.

Partial reconfiguration is supported through the FPP x16 configuration interface. You can seamlessly use partial reconfiguration in tandem with dynamic reconfiguration to enable simultaneous partial reconfiguration of both the device core and transceivers.

Enhanced Configuration and Configuration via Protocol

Table 23: Configuration Modes and Features of Arria V Devices

Arria V devices support 1.8 V, 2.5 V, 3.0 V, and 3.3 V[19] programming voltages and several configuration modes.

Mode	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps)	Decompressio	Design Security	Partial Reconfiguratio[20]	Remote System Update
AS through the EPCS and EPCQ serial configuration device	1 bit, 4 bits	100	—	Yes	Yes	—	Yes
PS through CPLD or external microcontroller	1 bit	125	125	Yes	Yes	—	—

[19] Arria V GZ does not support 3.3 V.
[20] Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Altera for support.

Mode	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps)	Decompressio	Design Security	Partial Reconfiguratio (20)	Remote System Update
FPP	8 bits	125	—	Yes	Yes	—	Parallel flash loader
	16 bits	125	—	Yes	Yes	Yes(21)	
	32 bits(22)	100	—	Yes	Yes	—	
CvP (PCIe)	x1, x2, x4, and x8 lanes	—	—	Yes	Yes	Yes	—
JTAG	1 bit	33	33	—	—	—	—
Configuration via HPS	16 bits	125	—	Yes	Yes	Yes (21)	Parallel flash loader
	32 bits	100	—	Yes	Yes	—	

Instead of using an external flash or ROM, you can configure the Arria V devices through PCIe using CvP. The CvP mode offers the fastest configuration rate and flexibility with the easy-to-use PCIe hard IP block interface. The Arria V CvP implementation conforms to the PCIe 100 ms power-up-to-active time requirement.

Note: Although Arria V GZ devices support PCIe Gen3, you can use only PCIe Gen1 and PCIe Gen2 for CvP configuration scheme.

Related Information

Configuration via Protocol (CvP) Implementation in Altera FPGAs User Guide
Provides more information about CvP.

Power Management

Leveraging the FPGA architectural features, process technology advancements, and transceivers that are designed for power efficiency, the Arria V devices consume less power than previous generation Arria V FPGAs:

- Total device core power consumption—less by up to 50%.
- Transceiver channel power consumption—less by up to 50%.

Additionally, Arria V devices contain several hard IP blocks, including PCIe Gen1, Gen2, and Gen3, GbE, SRIO, GPON, and CPRI protocols, that reduce logic resources and deliver substantial power savings of up to 25% less power than equivalent soft implementations.

(20) Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Altera for support.
(21) Supported at a maximum clock rate of 62.5 MHz.
(22) Arria V GZ only

Document Revision History

Date	Version	Changes
December 2015	2015.12.21	• Updated RoHS and optional suffix information in sample ordering code and available options diagrams for Arria V GX and GT devices. • Changed instances of *Quartus II* to *Quartus Prime*.
January 2015	2015.01.23	• Updated package dimension for Arria V GZ H780 package from 29 mm to 33 mm. • Updated dual-core ARM Cortex-A9 MPCore processor maximum frequency from 800 MHz to 1.05 GHz.
December 2013	2013.12.26	• 10-Gbps Ethernet (10GbE) PCS and Interlaken PCS are for Arria V GZ only. • Removed "Preliminary" texts from Ordering Code figures, Maximum Resources, Package Plan and I/O Vertical Migration tables. • Added link to **Altera Product Selector** for each device variant. • Added leaded package options. • Removed the note "The number of PLLs includes general-purpose fractional PLLs and transceiver fractional PLLs." for all PLLs in the Maximum Resource Counts table. • Corrected FPGA GPIO for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 F896 package from 170 to 250. • Corrected FPGA GPIO for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 F1152 package from 350 to 385. • Corrected FPGA GPIO for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 F1517 package from 528 to 540. • Corrected LVDS Transmitter for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 devices from 121 to 120. • Added links to Altera's **External Memory Spec Estimator** tool to the topics listing the external memory interface performance. • Added x2 for PCIe Gen3, Gen 2, and Gen 1.
August 2013	2013.08.19	• Removed the note about the PCIe hard IP on the right side of the device in the F896 package of the Arria V GX variant. These devices do not have PCIe hard IP on the right side. • Added transceiver speed grade 6 to the available options of the Arria V SX variant. • Corrected the maximum LVDS transmitter channel counts for the Arria V GX A1 and A3 devices from 68 to 67. • Corrected the maximum FPGA GPIO count for Arria V ST D5 devices from 540 to 528.